



US 20240213132A1

(19) **United States**

(12) **Patent Application Publication**
DARMAWIKARTA et al.

(10) **Pub. No.: US 2024/0213132 A1**

(43) **Pub. Date: Jun. 27, 2024**

(54) **THIN FILM CAPACITORS (TFCS) IN
ETCHED BACK DEEP VIA**

Publication Classification

(51) **Int. Cl.**

H01L 23/498 (2006.01)

H01L 27/01 (2006.01)

(52) **U.S. Cl.**

CPC **H01L 23/49838** (2013.01); **H01L 27/016**
(2013.01); **H01L 28/86** (2013.01); **H01L 28/90**
(2013.01); **H01L 23/49822** (2013.01); **H01L**
23/49894 (2013.01); **H01L 24/16** (2013.01)

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(21) Appl. No.: **18/089,476**

(22) Filed: **Dec. 27, 2022**

(57)

ABSTRACT

Embodiments disclosed herein include an electronic package. In an embodiment, the electronic package comprises a package substrate, where the package substrate comprises a plurality of stacked dielectric layers. In an embodiment, the electronic package further comprises an opening into the package substrate, where the opening passes through at least two of the plurality of dielectric layers. In an embodiment, a first pad is at the bottom of the opening, a capacitor is disposed in the opening, and a second pad is over the capacitor.

